



Form PTO-1449 (Rev. 8-83)		U.S. Department of Commerce		Atty. Docket No. D-21,389		Serial No.								
Information Disclosure Citation (Use several sheets if necessary)				Applicants Belov et al.										
				Filing Date		Group								
U.S. PATENT DOCUMENTS														
Examiner Initial		Document Number							Date	Name	Class	Subclass	Filing Date if Appropriate	
AD		4	5	2	5	6	3	1	6/1985	Allison	290	4		
		5	6	7	1	8	5	1	9/1997	Johnson et al.	211	51		
		5	7	3	8	8	0	0	4/1998	Hosali et al.	216	99		
		5	7	5	9	9	1	7	6/1998	Grover et al.	438	690		
		6	0	1	9	8	0	6	2/2000	Sees et al.	51	308		
		6	0	4	2	7	4	1	3/2000	Hosali et al.	252	79.1		
		6	1	1	4	2	4	9	9/2000	Canaperi et al.	438	692		
		6	1	3	2	6	3	7	10/2000	Hosali et al.	252	79.1		
		6	2	1	8	3	0	5	4/2001	Hosali et al.	438	691		
		6	2	3	8	4	9	4	5/2001	Segal	148	421		
AD		6	4	1	0	4	4	4	6/2002	Kido et al.	438	693		
FOREIGN PATENT DOCUMENTS														
		Document Number							Date	Country	Class	Subclass	Translation	
													Yes	No
Other Documents (including Author, Title, Date, Pertinent Pages, Etc.)														
AD		Cook, "Chemical Processes in Glass Polishing", Journal of Non-Crystalline Solids (1990) pp 152-171												
		Lo et al, "Characterization of Selective-CMP, Dummy Pattern and Reverse Mask Approaches in STI Planarization Process", Proceedings of 1999 CMP-MIC, pp-333-335												
		Lee et al., "The Effects of Slurries with Pattern Size and Step Height in Shallow Trench Isolation Chemical Mechanical Polishing", Proceedings of 2000 CMP-MIC, pp 288-290												
		Jin et al., "Advanced Front End CMP and Integration Solutions", Proceedings of 2000 CMP-MIC, pp 119-129												
		Bonner et al., "Development of a Direct Polish Process for Shallow Trench Isolation Modules", Proceedings of 2001 CMP-MIC, pp. 572-579												
AD		Xiao, "Introduction to Semiconductor Manufacturing Technology", Prentice-Hall Inc. (2001) pp. 384												
Examiner		Anthony Djini							Date Considered		2/7/05			
<small>* EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.</small>														

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Examiner Initial	Document Number							Date	Name	Class	Subclass	Filing Date if Appropriate	
AD	6	4	3	6	8	3	5	8/2002	Kido et al.	438	693		
	6	4	4	3	8	1	1	9/2002	Nojo et al.	451	41		
	6	4	7	1	7	3	5	10/2002	Misra et al.	51	308		
	0	1	4	2	6	0	0	10/2002	Jacquinet et al.*	438	690		
	0	1	9	5	4	2	1	12/2002	Srinivasan et al.*	216	38		
	0	0	0	6	3	9	7	1/2003	Srinivasan et al.*	252	79.1		
AD	6	5	4	4	8	9	2	4/2003	Srinivasan et al.	438	692		
	0	1	7	1	0	7	2	9/2003	Ward et al.*	451	28		
FOREIGN PATENT DOCUMENTS													
Examiner Initial	Document Number							Date	Country	Class	Subclass	Translation Yes No	
AD	8	4	6	7	4	0	6/1988	EP	-	-			
Other Documents (including Author, Title, Date, Pertinent Pages, Etc.)													
AD	Zhao et al, "Direct CMP for STT", Semiconductor International (2001) pp. 145-150												
	Bonner et al, "Improved Direct Polish STI CMP Process with High Selectivity Slurry:Reduced Microscratching & Increased Productivity", Proceedings of 2002 CMP-MIC, pp 247-254												
	Garliardi et al, "Fixed Abrasives and Selective Chemistries:Some Real Advantages for Direct STI CMP", Proceedings of 2002 CMP-MIC, pp 288-290												
	Tseng et al., "STI CMP Process with High - Selectivity Slurry", Proceedings of 2002 CMP-MIC, pp. 255-259												
	Leduc et al, "CMP:Aiming for Perfect Planarization", Proceedings of 2002 CMP-MIC, pp 239-246												
AD	Devriendt et al, "Challenges for the Integration of Shallow Trench Isolation", Proceedings of 2003 CMP-MIC, pp 492-500												
	EXAMINER Anthony Opini							Date Considered 2/7/05					
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